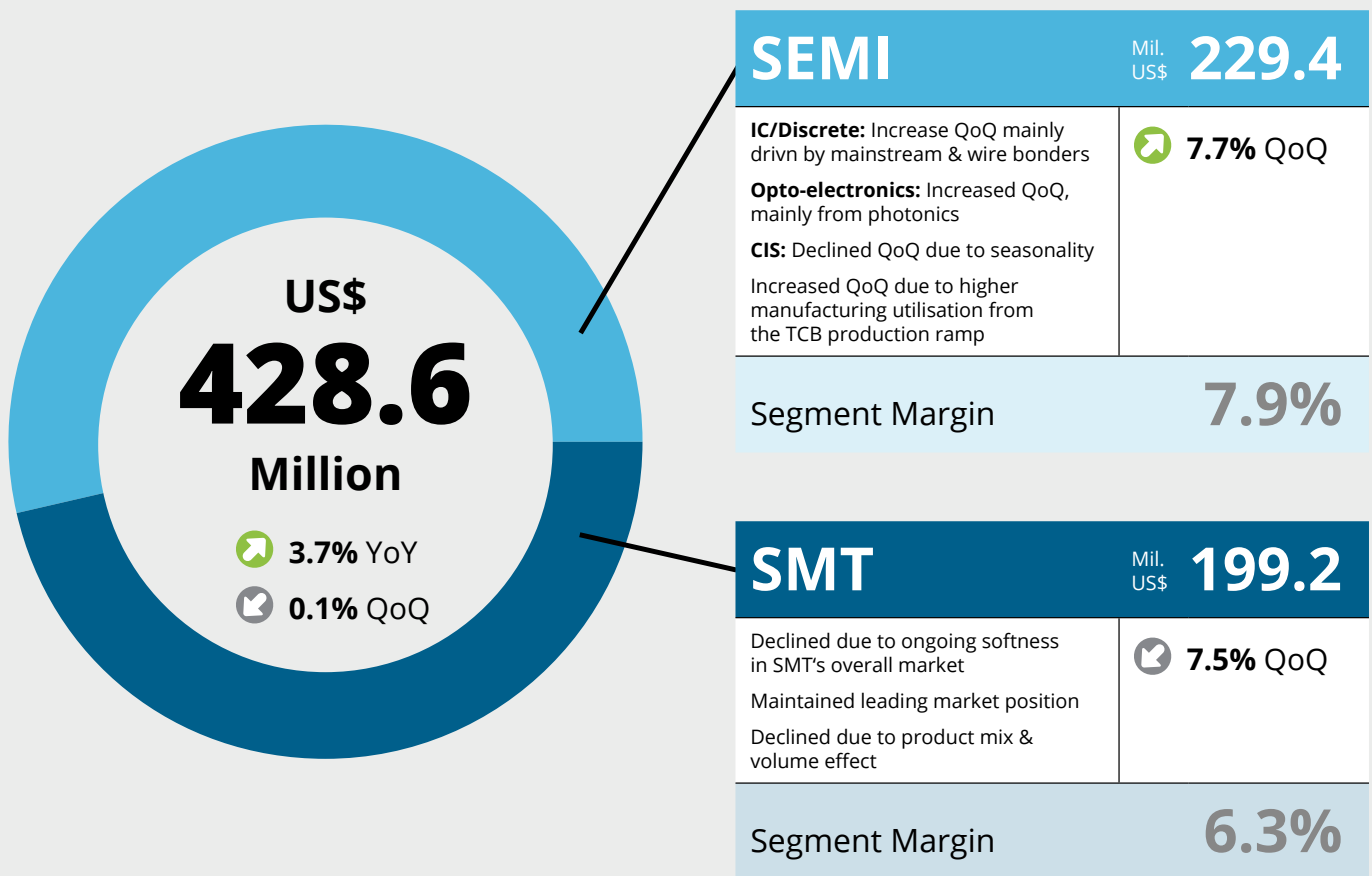


FINANCIAL RESULTS

LATEST FINANCIAL RESULTS

Q3 2024 Quarter Ended Sep 30, 2024



"Thanks to our exceptional expertise in the use of technologies and processes for electronics production and a consistent focus on the needs of our customers, we have become the undisputed number one in the SEMI and SMT segment. The expertise of our employees around the world is at the heart of this success."

Robin Ng, Chief Executive Officer, ASMPT



"The Group delivered revenue at the high end of this guidance, and it was flat quarter-on-quarter and down year-on-year. While SEMI registered revenue growth during this quarter, SMT's revenue was adversely impacted by the ongoing market softness. SEMI's revenue contribution to the Group was also higher than SMT's for this quarter. This portrays well the advantage of our broad-based portfolio as SEMI and SMT segments follow different business cycles and provides some stability at the group level."

Katie Xu Yifan, EVP & Chief Financial Officer, ASMPT

HIGHLIGHTS

Thermo Compression Bonding (TCB)

- Logic: Meaningful C2S orders from leading foundry's OSAT; shipment commenced in Q3
- High bandwidth memory („HBM“): Significant breakthrough with bulk order win from a leading player in October

Photonics

Meaningful order wins; in line with robust demand for 800G optical transceivers for data centres.

Silicon Photonics

Won orders for high-end optical communication related applications.

Hybrid Bonding

Shipped the first tool to a logic customer in Q3.